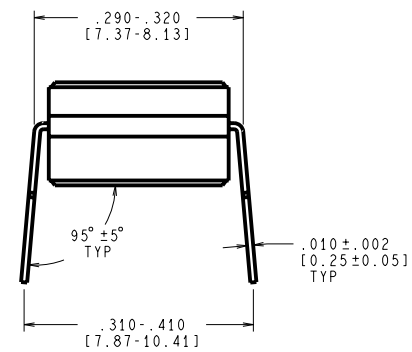
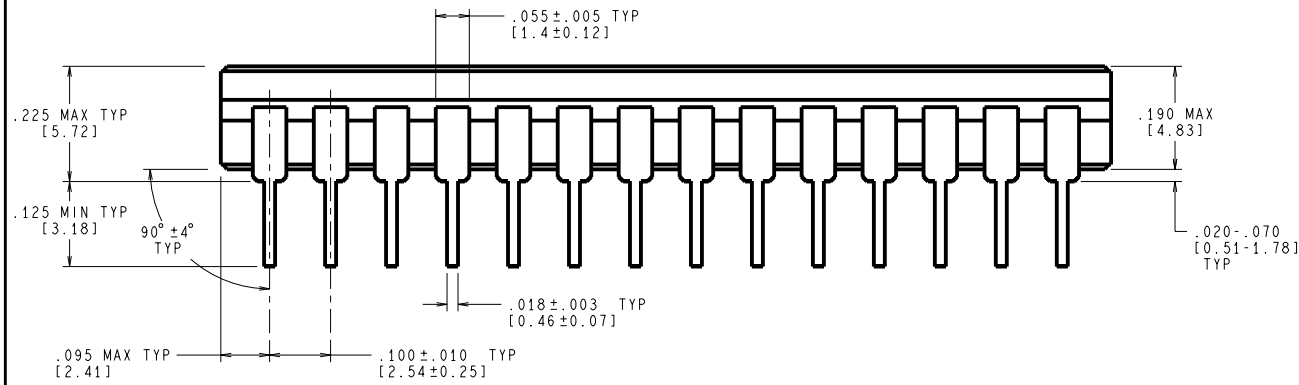
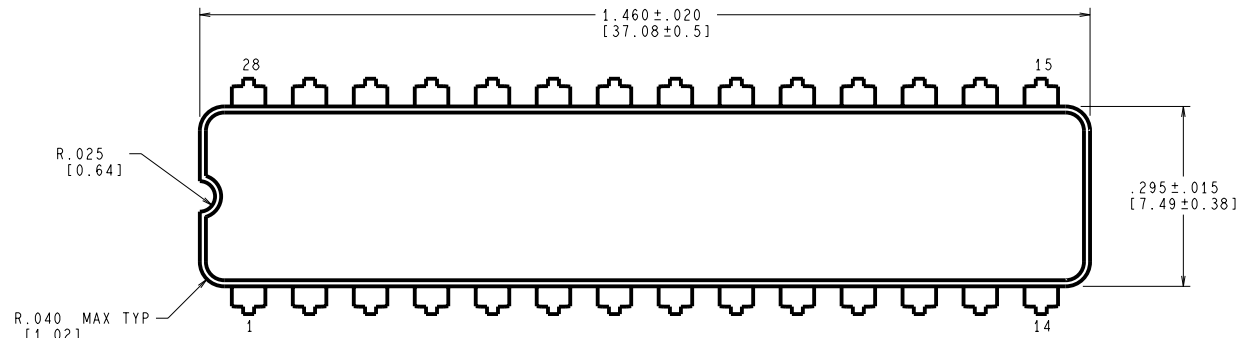


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11294	01/26/96	MS/



CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

MIL-PRF-38535
CONFIGURATION CONTROL

NOTES: UNLESS OTHERWISE SPECIFIED

- SOLDER DIPPED WITH Sn60 OR Sn63 SOLDER CONFORMING TO A MINIMUM THICKNESS OF 200 MICROINCHES/ 5.08 MICROMETERS. SOLDER MAY BE APPLIED OVER LEAD BASIS METAL OR Sn PLATE.
- MAXIMUM LIMIT MAY BE INCREASED BY .003 INCHES/ 0.08mm AFTER LEAD FINISH APPLIED.
- REFERENCE JEDEC REGISTRATION MO-058, VARIATION AB, DATED JULY 1989.

APPROVALS	DATE	National Semiconductor			
DRAWN MARTA SUCHY	01/26/96	2900 Semiconductor dr., Santa Clara, CA 95052-8090			
DFTG. CHK.		CERDIP, 28 LEAD, .300 CENTERS			
ENGR. CHK.					
 PROJECTION INCH [MM]		SCALE N/A	SIZE C	DRAWING NUMBER MKT-JA28A	REV A
		DO NOT SCALE DRAWING		SHEET 1 of 1	